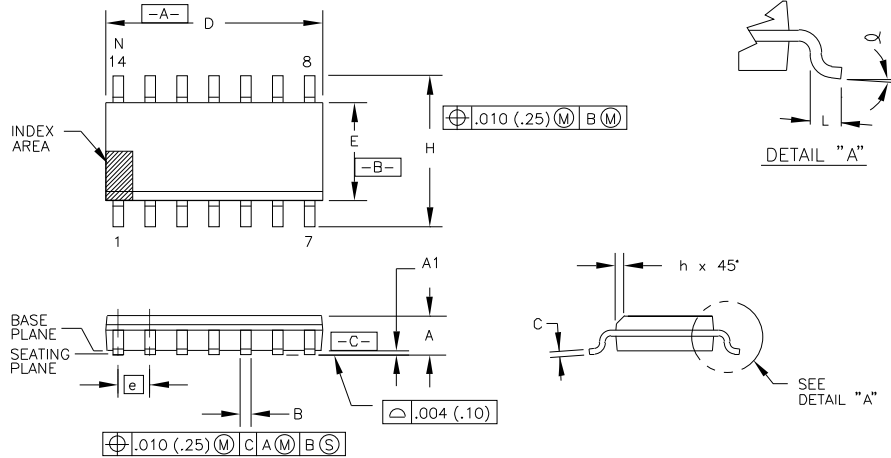


Package Number 235 - 14-Lead SOIC



DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	
A	.0532	.0688	1.35	1.75	
A1	.004	.0098	0.10	0.25	
B	.013	.020	0.33	0.51	7
C	.0075	.0098	0.19	0.25	
D	.3367	.3444	8.55	8.75	2
E	.1497	.1574	3.80	4.00	3
e	.050	BASIC	1.27	BASIC	
H	.2284	.244	5.80	6.20	
h	.0099	.0196	0.25	0.50	4
L	.016	.050	0.40	1.27	5
N	14		14		6
α	0°	8°	0°	8°	

- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
 - DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
 - DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
 - THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT,

- A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.
- L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
- N IS THE NUMBER OF TERMINAL POSITIONS.
- THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
- LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM SEATING PLANE.

PACKAGE NUMBER: Z2235 REV.: E
 JEDEC NUMBER: MS-012-AB



PACKAGE DRAWING

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